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ning of each regular issue of the PCT Gazette.

(54) Title: SILICON COMPOUNDS FOR PRODUCING SiO₂-CONTAINING INSULATING LAYERS ON CHIPS

(57) Abstract: The present invention relates to a process for producing an SiO₂-containing insulating layer on chips and the use of
specific precursors for this purpose. The invention further relates to an insulating layer obtainable in this way and also to chips which
have been provided with such an insulating layer.

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